

Correspondence of EPSON Quartz devices for RoHS directive

1. The relevant obligation of the RoHS directive for EPSON Quartz devices:

(1) Article 4:

Prevention

1. Member States shall ensure that, from 1 July 2006, new electrical and electronic equipment put on the market does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE). ...

* The definition of contain is now discussing in TAC(Technical Adaptation Committee) of EU.

2. Paragraph 1 shall not apply to the applications listed in the Annex. (The below items)

“5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.”

“7. – Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead).”

2. The current status of Quartz devices:

(1) The 5 substances (mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE)) which are prohibited by RoHS directive are not intentionally contained into Quartz devices.

(2) Seiko Epson corporation is now checking about possibility of the impurities which are 6 substances prohibited by RoHS directive.

(3) We have started supplying the Lead-free products* from April 2002 after getting the approval from customers.

(4) We will start shipping all products with no-substances prohibited by RoHS directive from factory on April 2004.

However, that will be arranged individually with customers who will not be able to approve the above switching.

* There are some Quartz devices containing lead internally. However, it is the exempted application listed in RoHS directive. (Please see Annex of RoHS directive.)

Contained lead in the sealing glass for some ceramic package products.

Contained lead in high melting temperature type solders for some plastic mold type products internally.